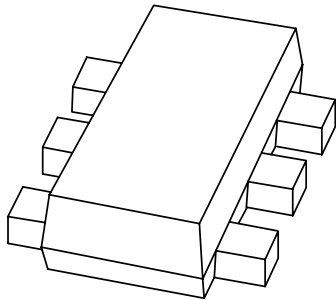


DATA SHEET



PEMF21 12 V PNP loadswitch

Product specification

2004 Jan 12

12 V PNP loadswitch

PEMF21

FEATURES

- Low V_{CEsat} transistor and resistor-equipped transistor in one package
- Very small 1.6×1.2 mm ultra thin package
- Reduced component count.

APPLICATIONS

- Line switches
- Battery charger switches
- Power supply switches
- Drive switches
- General purpose analog switches.

DESCRIPTION

Low V_{CEsat} PNP transistor and NPN resistor-equipped transistor in a SOT666 plastic package (see "Ordering information" for package details).

MARKING

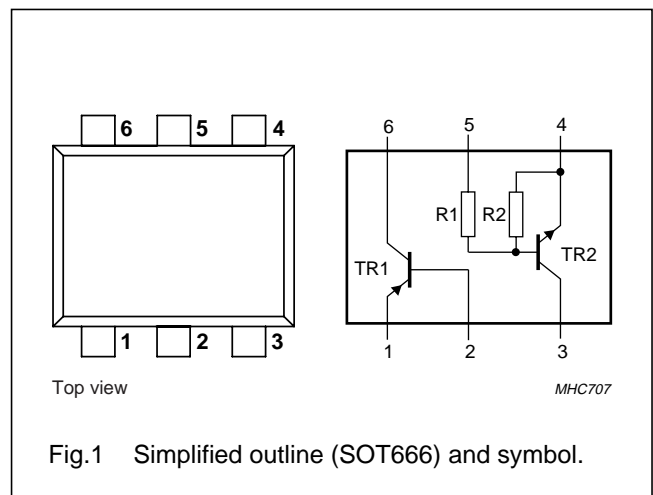
TYPE NUMBER	MARKING CODE
PEMF21	2F

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
TR1; PNP; low V_{CEsat} transistor				
V_{CEO}	collector-emitter voltage	–	–12	V
I_C	collector current (DC)	–	–500	mA
R_{CEsat}	equivalent on-resistance	–	500	m Ω
TR2; NPN; resistor-equipped transistor				
V_{CEO}	collector-emitter voltage	–	50	V
I_O	output current (DC)	–	100	mA
R1	bias resistor	10	–	k Ω
R2	bias resistor	10	–	k Ω

PINNING

PIN	DESCRIPTION
1	emitter TR1
2	base TR1
3	collector TR2
4	emitter TR2
5	base TR2
6	collector TR1



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PEMF21	–	plastic surface mounted package; 6 leads	SOT666

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Transistor TR1					
V _{CBO}	collector-base voltage	open emitter	–	–15	V
V _{CEO}	collector-emitter voltage	open base	–	–12	V
V _{EBO}	emitter-base voltage	open collector	–	–6	V
I _C	collector current (DC)		–	–500	mA
I _{CM}	peak collector current		–	–1	A
I _{BM}	peak base current		–	–100	mA
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	–	200	mW
Transistor TR2					
V _{CBO}	collector-base voltage	open emitter	–	50	V
V _{CEO}	collector-emitter voltage	open base	–	50	V
V _{EBO}	emitter-base voltage	open collector	–	10	V
V _i	input voltage				
	positive		–	+40	V
	negative		–	–10	V
I _O	output current (DC)		–	100	mA
I _{CM}	peak collector current		–	100	mA
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	–	200	mW
Per device					
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	–	300	mW
T _{stg}	storage temperature		–65	+150	°C
T _j	junction temperature		–	150	°C
T _{amb}	operating ambient temperature		–65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
Per device				
R _{th(j-a)}	thermal resistance from junction to ambient	notes 1 and 2	416	K/W

Notes

1. Transistor mounted on an FR4 printed-circuit board.
2. Reflow soldering is the only recommended soldering method.

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CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

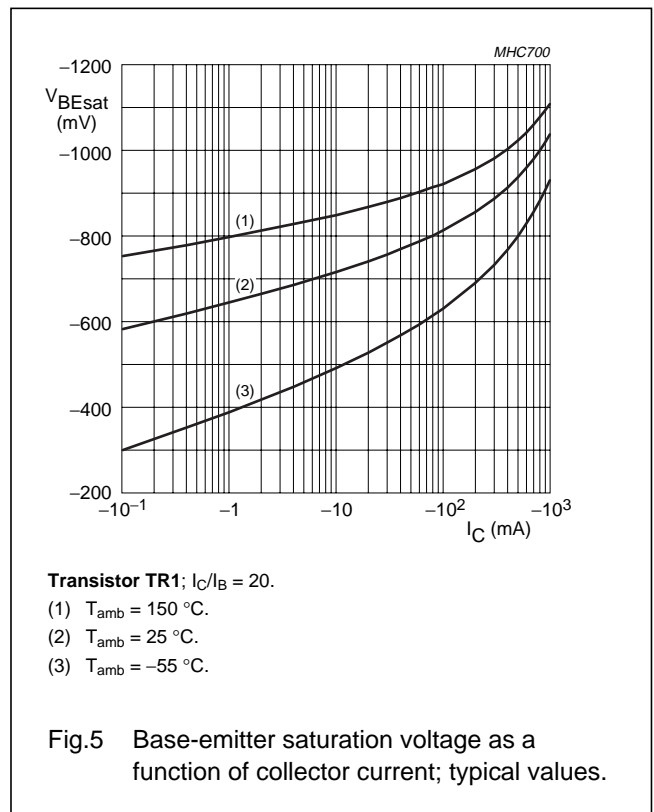
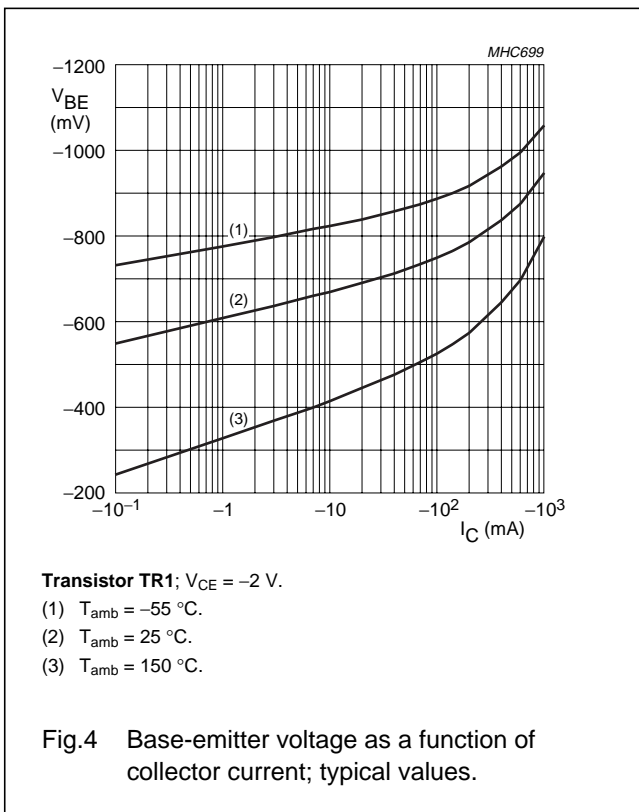
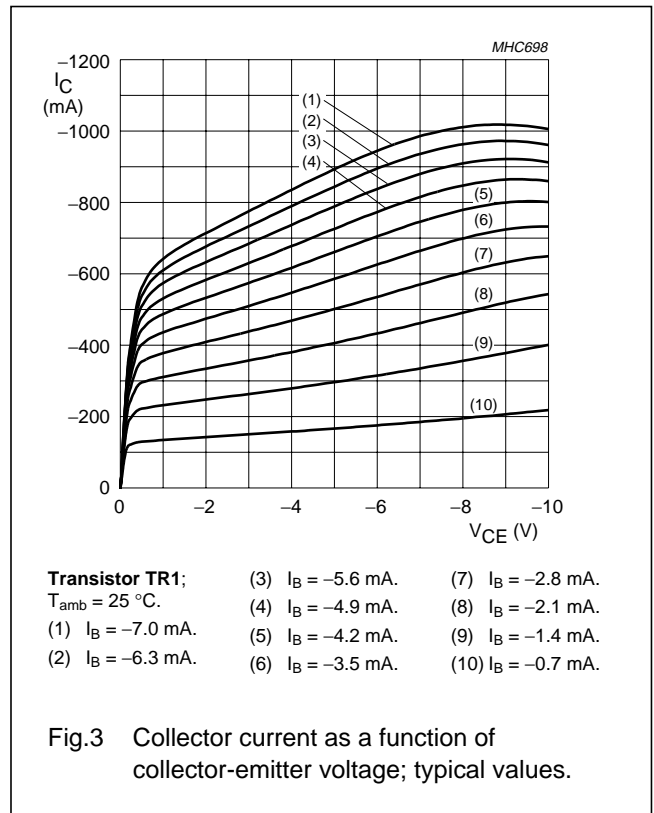
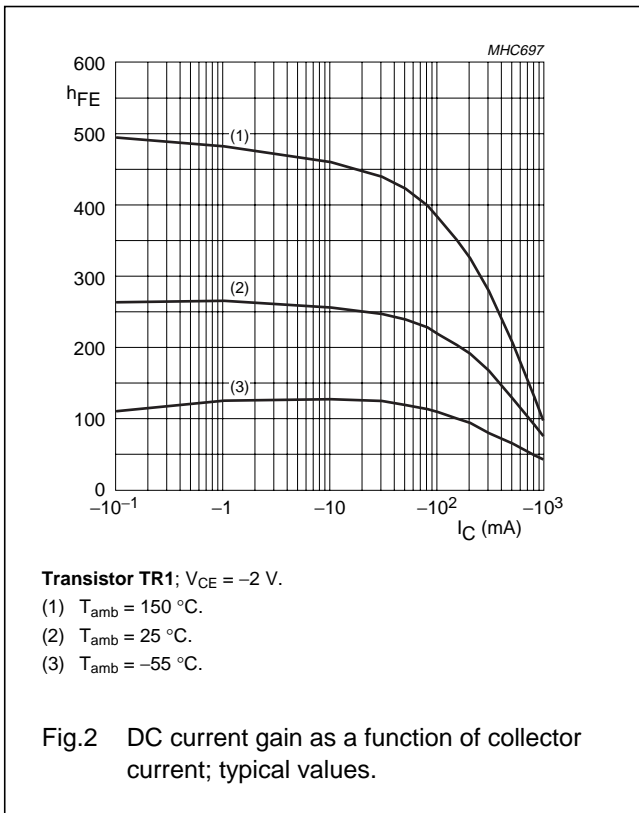
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Transistor TR1						
I_{CBO}	collector-base cut-off current	$V_{CB} = -15\text{ V}; I_E = 0$	–	–	–100	nA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0$	–	–	–100	nA
h_{FE}	DC current gain	$V_{CE} = -2\text{ V}; I_C = -10\text{ mA}$	200	–	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -200\text{ mA}; I_B = -10\text{ mA}$	–	–	–250	mV
R_{CEsat}	equivalent on-resistance	$I_C = -500\text{ mA}; I_B = -50\text{ mA}; \text{note 1}$	–	300	500	$\text{m}\Omega$
V_{BEsat}	base-emitter saturation voltage	$I_C = -500\text{ mA}; I_B = -50\text{ mA}; \text{note 1}$	–	–	–1.1	V
V_{BEon}	base-emitter turn-on voltage	$V_{CE} = -2\text{ V}; I_C = -100\text{ mA}; \text{note 1}$	–	–	–0.9	V
f_T	transition frequency	$I_C = -100\text{ mA}; V_{CE} = -5\text{ V}; f = 100\text{ MHz}$	100	280	–	MHz
C_c	collector capacitance	$V_{CB} = -10\text{ V}; I_E = i_e = 0; f = 1\text{ MHz}$	–	–	10	pF
Transistor TR2						
I_{CBO}	collector-base cut-off current	$V_{CB} = 50\text{ V}; I_E = 0$	–	–	100	nA
I_{CEO}	collector-emitter cut-off current	$V_{CE} = 30\text{ V}; I_B = 0$	–	–	1	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_C = 0$	–	–	400	μA
h_{FE}	DC current gain	$V_{CE} = 5\text{ V}; I_C = 5\text{ mA}$	30	–	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	–	–	300	mV
$V_{i(off)}$	input-off voltage	$V_{CE} = 5\text{ V}; I_C = 100\text{ }\mu\text{A}$	–	–	0.5	V
$V_{i(on)}$	input-on voltage	$V_{CE} = 0.3\text{ V}; I_C = 10\text{ mA}$	3	–	–	V
R1	input resistor		7	10	13	$\text{k}\Omega$
$\frac{R2}{R1}$	resistor ratio		0.8	1	1.2	
C_c	collector capacitance	$V_{CB} = 10\text{ V}; I_E = i_e = 0; f = 1\text{ MHz}$	–	–	2.5	pF

Note

1. Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.

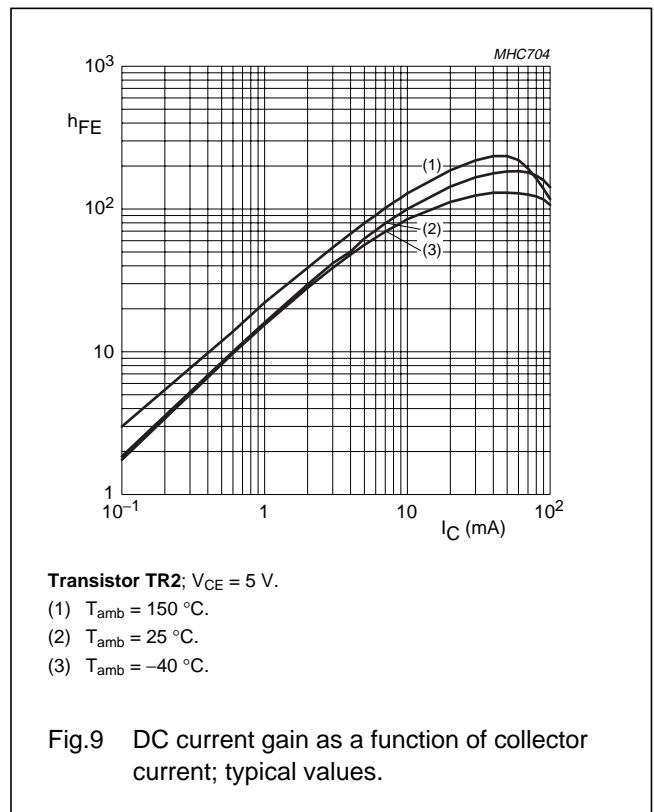
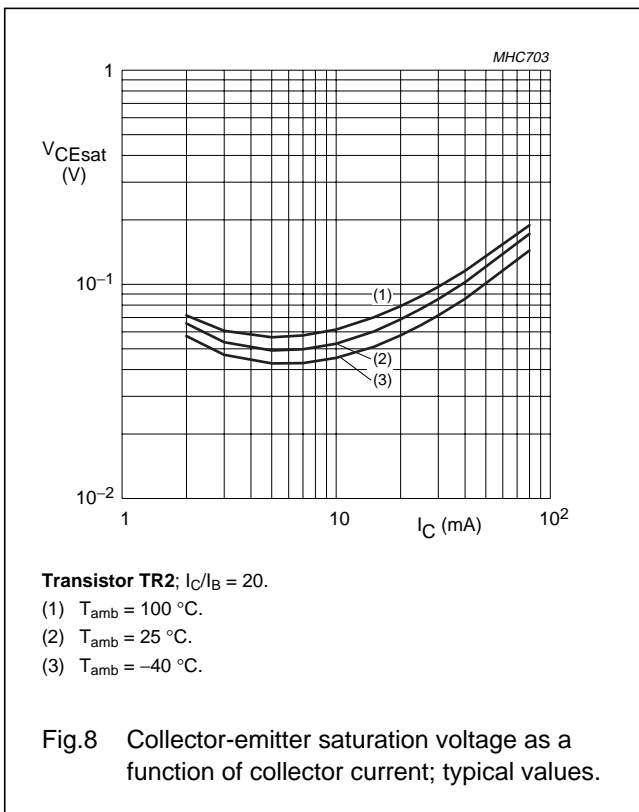
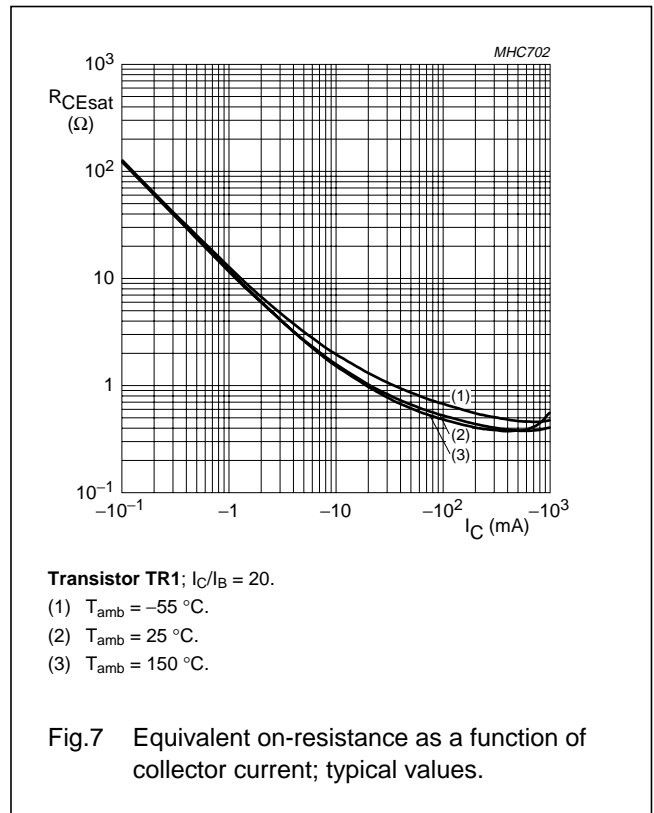
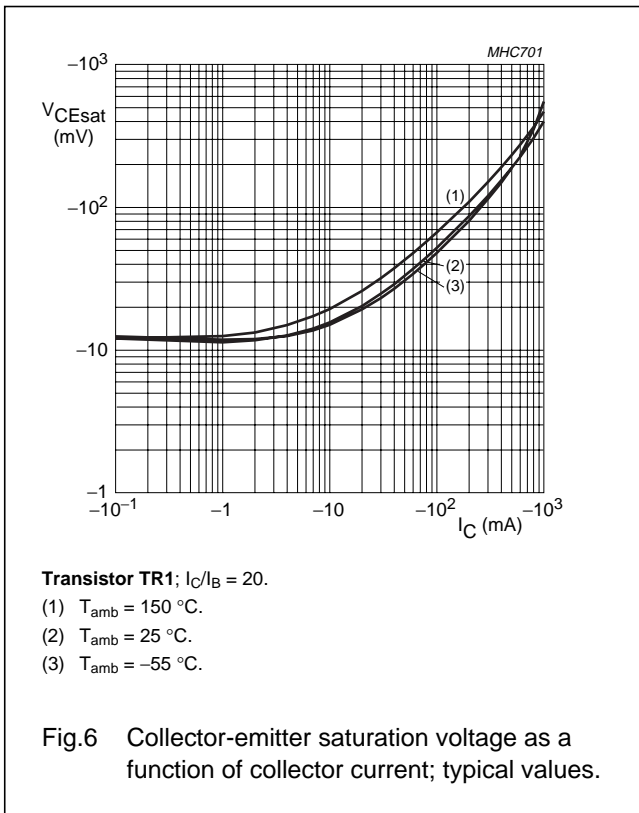
12 V PNP loadswitch

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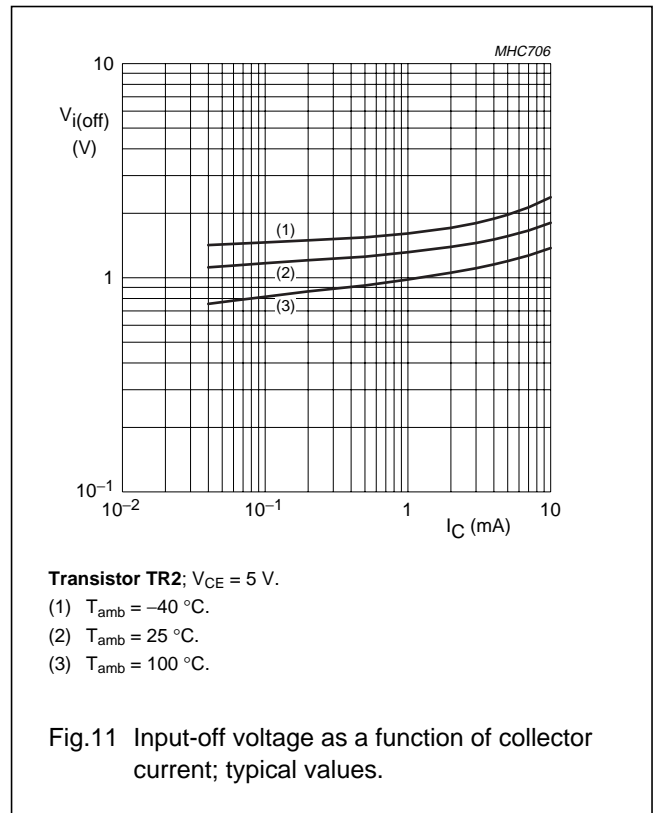
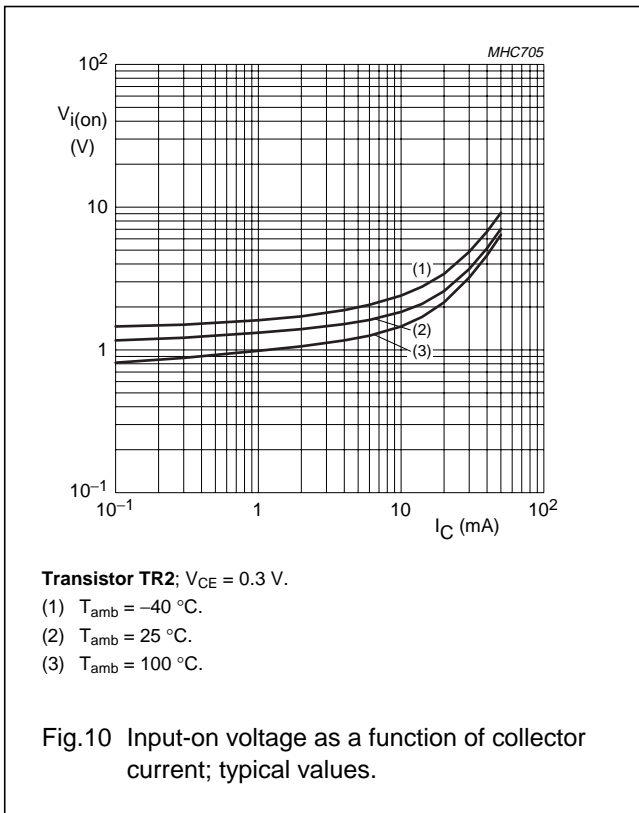
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12 V PNP loadswitch

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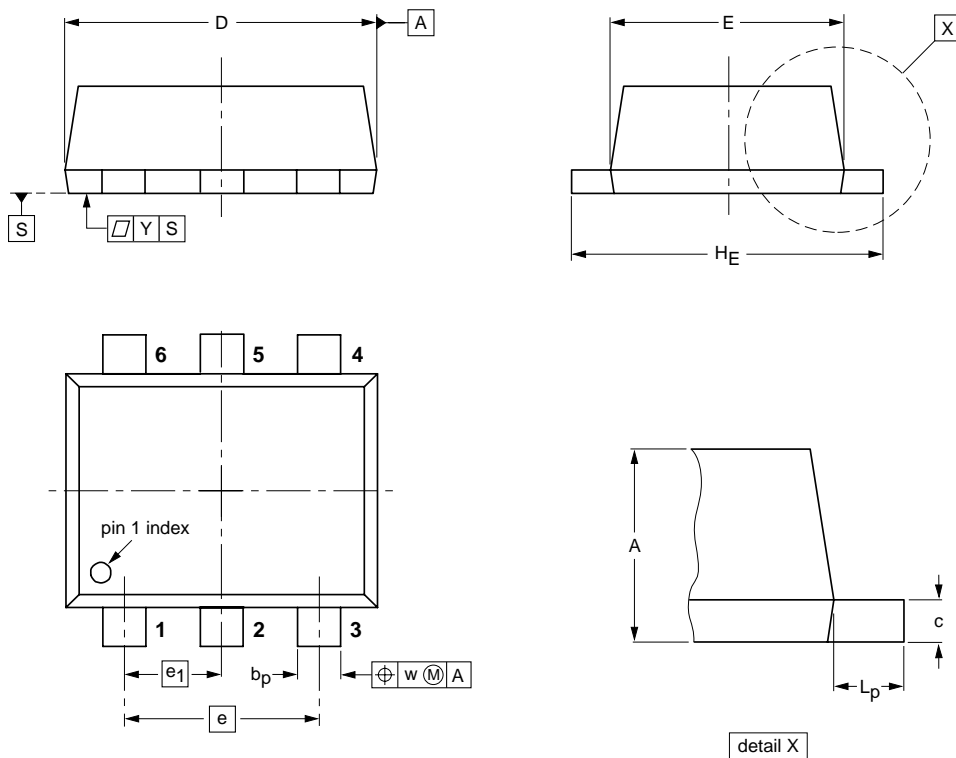
12 V PNP loadswitch

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PACKAGE OUTLINE

Plastic surface mounted package; 6 leads

SOT666



DIMENSIONS (mm are the original dimensions)

UNIT	A	b_p	c	D	E	e	e_1	H_E	L_p	w	y
mm	0.6 0.5	0.27 0.17	0.18 0.08	1.7 1.5	1.3 1.1	1.0	0.5	1.7 1.5	0.3 0.1	0.1	0.1

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT666					01-01-04 01-08-27

12 V PNP loadswitch

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Printed in The Netherlands

R75/01/pp10

Date of release: 2004 Jan 12

Document order number: 9397 750 12204

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